

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.0041	0.85	0.06205
	Doped silicon	Silicon (Si)	7440-21-3	0.47783	99.15	7.23795
		Subtotal		0.48193	100	7.3
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.02645	10.0	0.4007
	Silver alloy	Silver (Ag)	7440-22-4	0.00529	2.0	0.08014
	Lead alloy	Lead (Pb)	7439-92-1	0.23279	88.0	3.52615
		Subtotal		0.26453	100	4.00699
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.56698	100.0	8.58835
		Subtotal		0.56698	100	8.58835
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00922	0.03	0.13965
	Copper alloy	Iron (Fe)	7439-89-6	0.0338	0.11	0.51205
	Copper alloy	Copper (Cu)	7440-50-8	30.68821	99.86	464.8483
		Subtotal		30.73123	100	465.5
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.32019	100.0	4.85
		Subtotal		0.32019	100	4.85
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.41081	8.0	81.96
	Filler	Silica fused	60676-86-0	54.78446	81.0	829.845
	Metal hydroxide	Metal hydroxide		0.47345	0.7	7.1715
	Carbon Black	Carbon black	1333-86-4	0.20291	0.3	3.0735
	Polymer	Epoxy resin system		6.76351	10.0	102.45
		Subtotal		67.63514	100	1024.5
		Total		100	100	1514.74534

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.